

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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MPS6652 is a Preferred Device

Amplifier Transistors

Features

- Voltage and Current are Negative for PNP Transistors
- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage MPS6601/6651 MPS6652	V _{CEO}	25 40	Vdc
Collector – Base Voltage MPS6601/6651 MPS6652	V _{CBO}	25 30	Vdc
Emitter-Base Voltage	V _{EBO}	4.0	Vdc
Collector Current – Continuous	I _C	1000	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	W mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction–to–Ambient (Note 1)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

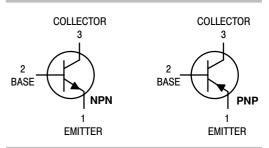
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

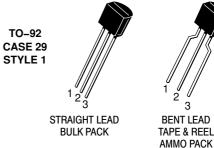
1. R_{0.IA} is measured with the device soldered into a typical printed circuit board.

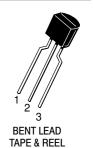


ON Semiconductor®

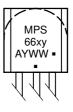
http://onsemi.com







MARKING DIAGRAM



MPS66xv = Device Code

x = 0 or 5

y = 1 or 2

Α = Assembly Location

WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Chara	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS				1	•
Collector – Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MPS6601/6651 MPS6652	V _{(BR)CEO}	25 40	_ _	Vdc
Collector – Base Breakdown Voltage ($I_C = 100 \mu Adc, I_E = 0$)	MPS6601/6651 MPS6652	V _{(BR)CBO}	25 40	_ _	Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$)		V _{(BR)EBO}	4.0	-	Vdc
	MPS6601/6651 MPS6652	I _{CES}	- -	0.1 0.1	μAdc
	MPS6601/6651 MPS6652	Ісво	- -	0.1 0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 100 \text{ mAdc}$, $V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 500 \text{ mAdc}$, $V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 1000 \text{ mAdc}$, $V_{CE} = 1.0 \text{ Vdc}$)		h _{FE}	50 50 30	_ _ _	-
		V _{CE(sat)}	-	0.6	Vdc
Base-Emitter On Voltage (I _C = 500 mAdc, V _{CE} = 1.0 Vdc)		V _{BE(on)}	-	1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS	}		•	•	
Current – Gain — Bandwidth Product $(I_C = 50 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 10 \text{ Vdc})$	00 MHz)	f _T	100	-	MHz
Output Capacitance $(V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$		C _{obo}	_	30	pF
SWITCHING CHARACTERISTICS					
Delay Time		t _d	-	25	ns
Rise Time	$(V_{CC} = 40 \text{ Vdc}, I_{C} = 500 \text{ mAdc}, I_{B1} = 50 \text{ mAdc},$	t _r	-	30	ns
Storage Time	$t_{p} \ge 300 \text{ ns Duty Cycle})$	ts	-	250	ns
Fall Time		t _f	-	50	ns

ORDERING INFORMATION

OIDEITHA IN OTHER TON			
Device	Package	Shipping [†]	
MPS6601RLRAG	TO-92 (TO-226) (Pb-Free)	2000 Units / Tape & Reel	
MPS6651G	TO-92 (TO-226) (Pb-Free)		
MPS6652	TO-92 (TO-226)	5000 Units / Bulk	
MPS6652G	TO-92 (TO-226) (Pb-Free)		
MPS6652RLRAG	TO-92 (TO-226) (Pb-Free)	2000 Units / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

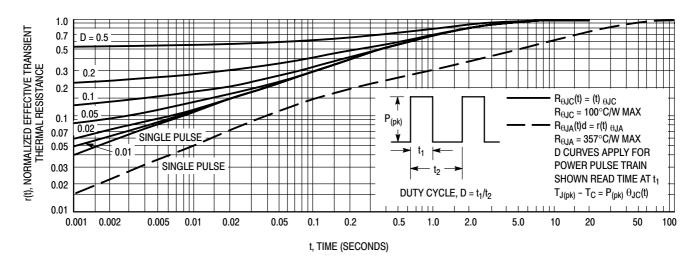
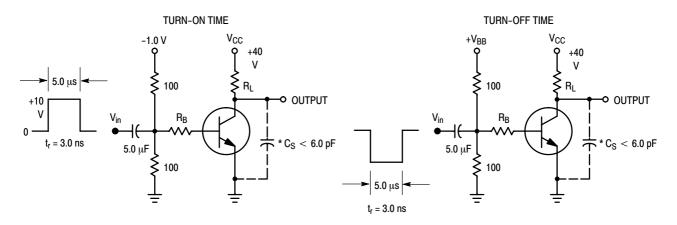


Figure 1. Thermal Response



*Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 2. Switching Time Test Circuits

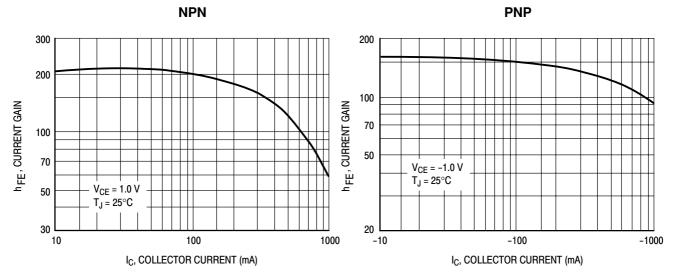


Figure 3. MPS6601/6602 DC Current Gain

Figure 4. MPS6651/6652 DC Current Gain

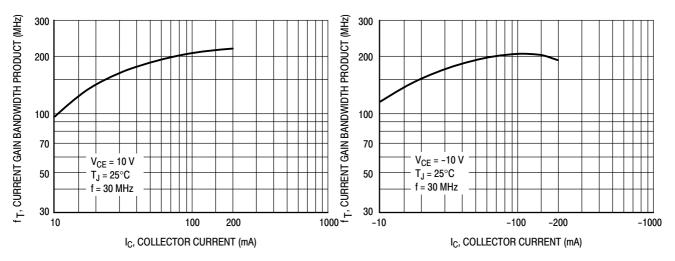
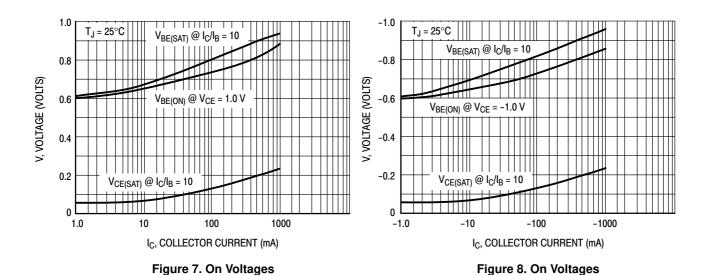


Figure 5. Current Gain Bandwidth Product

Figure 6. Current Gain Bandwidth Product



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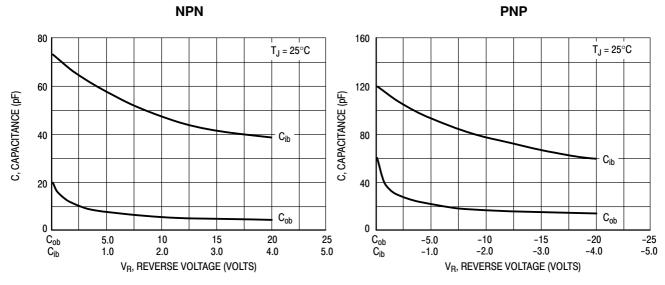


Figure 9. Capacitance

Figure 10. Capacitance

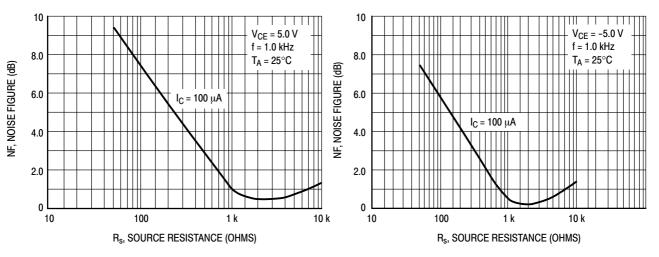


Figure 11. MPS6601/6602 Noise Figure

Figure 12. MPS6651/6652 Noise Figure

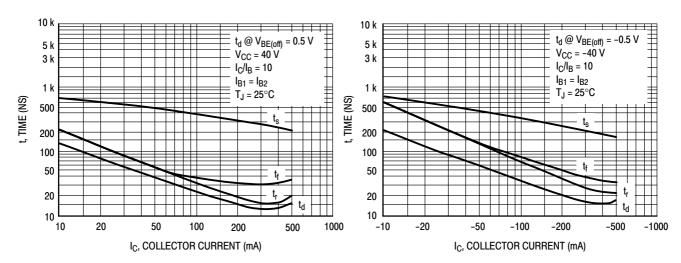


Figure 13. MPS6601/6602 Switching Times

Figure 14. MPS6651/6652 Switching Times

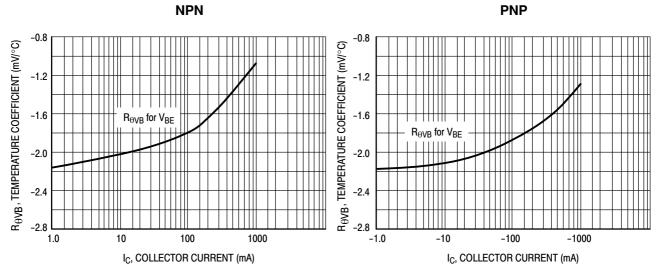


Figure 15. Base–Emitter Temperature Coefficient

Figure 16. Base–Emitter Temperature Coefficient

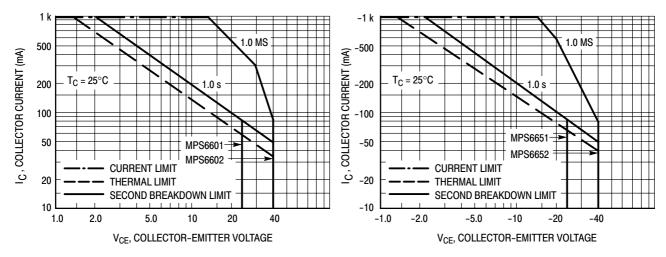


Figure 17. Safe Operating Area

Figure 18. Safe Operating Area

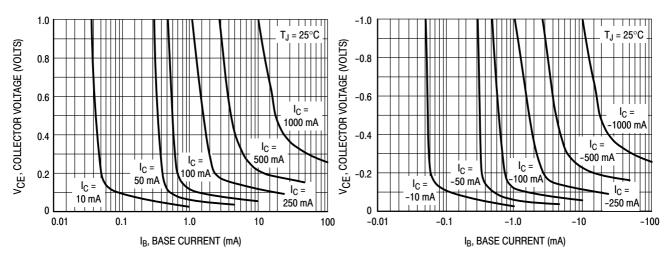
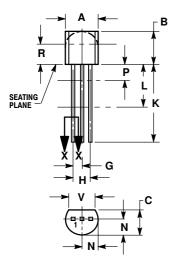


Figure 19. MPS6601/6602 Saturation Region

Figure 20. MPS6651/6652 Saturation Region

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AM



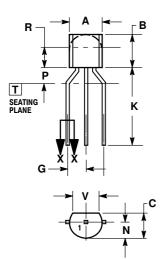
STRAIGHT LEAD **BULK PACK**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	



BENT LEAD TAPE & REEL AMMO PACK



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 CONTOUR OF PACKAGE BEYOND
- DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN PAND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN MAX		
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
V	3.43		

PIN 1 FMITTER

BASE

COLLECTOR

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